

2. (Amended) The frame of Claim 1, wherein the thin parts are formed by half-etching metal at the connection areas from the front or back of the frame.

3. (Amended) A frame for semiconductor packages comprising plural lead frames arranged in a matrix through grid-leads, the grid-leads having terminals which project therefrom and terminals of adjacent pairs of lead frames are connected to one another at respective connection areas, semiconductor devices being respectively mounted on die-pads supported with suspending leads of individual lead frames, the semiconductor devices being collectively molded with molding compound, and the collectively molded semiconductor devices being cut along the grid-leads into individual semiconductor packages, wherein hollows are formed adjacent roots of individual terminals, the terminal roots being disposed in the respective connection areas defined between interconnected pairs of terminals of adjacent lead frames.

Please add Claims 4-16 as follows:

4. (New) A frame for forming individual semiconductor packages, said frame comprising a plurality of lead frames arranged in a matrix and semiconductor devices respectively mounted on die pads supported on the individual lead frames by suspending leads, each said lead frame having a metal lead which defines a boundary between said lead frame and an adjacent lead frame, and pairs of terminals project in opposite directions from each said lead disposed between an adjacent pair of lead frames, wherein roots of the respective pairs of interconnected terminals disposed closely adjacent the corresponding lead and projecting outwardly therefrom each have a reduced thickness such that a maximum distance is

maintained between laterally adjacent pairs of roots of individual lead frames.

5. (New) The frame of Claim 4 wherein said roots comprise half-etched areas to reduce the thickness thereof such that after cutting of said frame along said leads to form individual semiconductor packages, said half-etched areas of said roots are exposed and located at the outer peripheries of the respective semiconductor packages.

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6. (New) The frame of Claim 4 wherein said roots of each interconnected pair of terminals of interconnected lead frames and a portion of the corresponding said lead disposed between said roots are half-etched.

7. (New) The frame of Claim 4 wherein said roots comprise half-etched areas to reduce the thickness thereof as defined between front and rear sides of said frame.

8. (New) The frame of Claim 4 wherein said terminals of each said lead frame are disposed outwardly of the respective said die pad in surrounding relation therewith.

9. (New) The frame of Claim 8 wherein said semiconductor devices are electrically connected to said terminals of the corresponding said lead frame by wires.

10. (New) The frame of Claim 9 wherein said frame defines at least one cavity therein, said lead frames and the corresponding said semiconductor devices being disposed in said cavity, said frame further comprising molding compound disposed in said cavity so as to encapsulate upper sides of said semiconductor devices and lower sides of said die pads.

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11. (New) A frame for forming individual semiconductor packages, said frame comprising a plurality of lead frames arranged in a matrix and semiconductor devices respectively mounted on die pads supported on the individual lead frames by suspending leads, each said lead frame having a metal lead which defines a boundary between said lead frame and an adjacent said lead frame, and pairs of terminals project in opposite directions from each said lead disposed between an adjacent pair of lead frames, each said terminal having a root disposed closely adjacent and projecting from the corresponding said lead, and each said root being recessed inwardly on opposite sides thereof to define a hollow between laterally adjacent pairs of roots of the individual lead frames such that a maximum distance is maintained therebetween.

12. (New) The frame of Claim 11 wherein said hollows defined between laterally adjacent pairs of roots of the individual lead frames each additionally extend into a portion of the corresponding said lead which extends transversely between each laterally adjacent pair of roots.

13. (New) The frame of Claim 12 wherein each said hollow has a rounded shape.

14. (New) The frame of Claim 11 wherein said terminals of each said lead frame are disposed outwardly of the respective said die pad in surrounding relation therewith.

15. (New) The frame of Claim 14 wherein said semiconductor devices are electrically connected to said terminals of the corresponding said lead frame by wires.